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January 2008

# 74AC240, 74ACT240 Octal Buffer/Line Driver with 3-STATE Outputs

#### **Features**

- I<sub>CC</sub> and I<sub>OZ</sub> reduced by 50%
- Inverting 3-STATE outputs drive bus lines or buffer memory address registers
- Outputs source/sink 24mA
- ACT240 has TTL-compatible inputs

### **General Description**

The AC/ACT240 is an octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus oriented transmitter or receiver which provides improved PC board density.

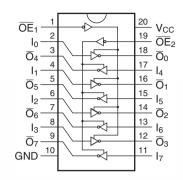
### **Ordering Information**

Order Number	Package Number	Package Description
74AC240SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74AC240SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74AC240MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74AC240PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
74ACT240SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ACT240SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ACT240MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ACT240PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

### **Connection Diagram**

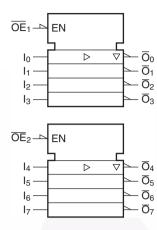


### **Pin Description**

Pin Names	Description
$\overline{OE}_1$ , $\overline{OE}_2$	3-STATE Output Enable Inputs
I <sub>0</sub> —I <sub>7</sub>	Inputs
$\overline{O}_0$ – $\overline{O}_7$	Outputs

### **Logic Symbol**

#### IEEE/IEC



### **Truth Tables**

Inp	uts	Outputs
OE <sub>1</sub>	In	(Pins 12, 14, 16, 18)
L	L	Н
L	Н	L
Н	Х	Z

Inputs		Outputs
OE <sub>2</sub>	In	(Pins 3, 5, 7, 9)
L	L	Н
L	Н	L
Н	Х	Z

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	-0.5V to +7.0V
I <sub>IK</sub>	DC Input Diode Current	
	$V_{I} = -0.5V$	–20mA
	$V_{I} = V_{CC} + 0.5$	+20mA
VI	DC Input Voltage	-0.5V to V <sub>CC</sub> + 0.5V
I <sub>OK</sub>	DC Output Diode Current	
	$V_{O} = -0.5V$	-20mA
	$V_{O} = V_{CC} + 0.5V$	+20mA
V <sub>O</sub>	DC Output Voltage	-0.5V to V <sub>CC</sub> + 0.5V
Io	DC Output Source or Sink Current	±50mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current per Output Pin	±50mA
T <sub>STG</sub>	Storage Temperature	−65°C to +150°C
TJ	Junction Temperature	140°C

### **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating		
V <sub>CC</sub>	Supply Voltage			
	AC	2.0V to 6.0V		
	ACT	4.5V to 5.5V		
VI	Input Voltage			
Vo	Output Voltage	0V to V <sub>CC</sub>		
T <sub>A</sub>	Operating Temperature -40°C to +8			
ΔV / Δt	Minimum Input Edge Rate, AC Devices: 125mV/i			
	V <sub>IN</sub> from 30% to 70% of V <sub>CC</sub> , V <sub>CC</sub> @ 3.3V, 4.5V, 5.5V			
ΔV / Δt	Minimum Input Edge Rate, ACT Devices: 125mV/r			
	V <sub>IN</sub> from 0.8V to 2.0V, V <sub>CC</sub> @ 4.5V, 5.5V			

### **DC Electrical Characteristics for AC**

				<b>T</b> <sub>A</sub> = -	+25°C	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Тур.	G	uaranteed Limits	Units
V <sub>IH</sub>	Minimum HIGH Level	3.0	V <sub>OUT</sub> = 0.1V or	1.5	2.1	2.1	V
	Input Voltage	4.5	V <sub>CC</sub> – 0.1V	2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V <sub>IL</sub>	Maximum LOW Level	3.0	V <sub>OUT</sub> = 0.1V or	1.5	0.9	0.9	V
	Input Voltage	4.5	V <sub>CC</sub> – 0.1V	2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V <sub>OH</sub>	Minimum HIGH Level	3.0	I <sub>OUT</sub> = -50μA	2.99	2.9	2.9	V
	Output Voltage	4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -12\text{mA}$		2.56	2.46	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(1)}$		4.86	4.76	
V <sub>OL</sub>	Maximum LOW Level	3.0	I <sub>OUT</sub> = 50μA	0.002	0.1	0.1	V
	Output Voltage	4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 12\text{mA}$		0.36	0.44	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(1)}$		0.36	0.44	
I <sub>IN</sub> <sup>(2)</sup>	Maximum Input Leakage Current	5.5	V <sub>I</sub> = V <sub>CC</sub> , GND		±0.1	±1.0	μA
I <sub>OZ</sub>	Maximum 3-STATE Leakage Current	5.5	$\begin{aligned} &V_{I}\left(OE\right)=V_{IL},V_{IH};\\ &V_{I}=V_{CC},GND;\\ &V_{O}=V_{CC},GND \end{aligned}$		±0.25	±2.5	μА
I <sub>OLD</sub>	Minimum Dynamic	5.5	V <sub>OLD</sub> = 1.65V Max.			75	mA
I <sub>OHD</sub>	Output Current <sup>(3)</sup>	5.5	V <sub>OHD</sub> = 3.85V Min.			-75	mA
I <sub>CC</sub> <sup>(2)</sup>	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

#### Notes:

- 1. All outputs loaded; thresholds on input associated with output under test.
- 2.  $I_{\text{IN}}$  and  $I_{\text{CC}}$  @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V  $V_{\text{CC}}.$
- 3. Maximum test duration 2.0ms, one output loaded at a time.

### **DC Electrical Characteristics for ACT**

				<b>T</b> <sub>A</sub> = -	+25°C	$T_A = -40^{\circ}C$ to $+85^{\circ}C$	
Symbol	Parameter	$V_{CC}(V)$	Conditions	Тур.	G	uaranteed Limits	Units
V <sub>IH</sub>	Minimum HIGH Level	4.5	$V_{OUT} = 0.1V$ or	1.5	2.0	2.0	V
	Input Voltage	5.5	V <sub>CC</sub> – 0.1V	1.5	2.0	2.0	
V <sub>IL</sub>	Maximum LOW	4.5	$V_{OUT} = 0.1V$ or	1.5	0.8	0.8	V
	Level Input Voltage	5.5	V <sub>CC</sub> – 0.1V	1.5	0.8	0.8	
V <sub>OH</sub>	Minimum HIGH Level	4.5	$I_{OUT} = -50\mu A$	4.49	4.4	4.4	V
	Output Voltage	5.5		5.49	5.4	5.4	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(4)}$		4.86	4.76	
V <sub>OL</sub>	Maximum LOW	4.5	$I_{OUT} = 50\mu A$	0.001	0.1	0.1	V
	Level Output Voltage	5.5		0.001	0.1	0.1	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(4)}$		0.36	0.44	
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$ , GND		±0.1	±1.0	μΑ
I <sub>OZ</sub>	Maximum 3-STATE Leakage Current	5.5	$V_I = V_{IL}, V_{IH};$ $V_O = V_{CC}, GND$		±0.25	±2.5	μA
I <sub>CCT</sub>	Maximum I <sub>CC</sub> /Input	5.5	$V_I = V_{CC} - 2.1V$	0.6		1.5	mA
I <sub>OLD</sub>	Minimum Dynamic	5.5	V <sub>OLD</sub> = 1.65V Max.			75	mA
I <sub>OHD</sub>	Output Current <sup>(5)</sup>	5.5	V <sub>OHD</sub> = 3.85V Min.			<b>-75</b>	mA
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μΑ

#### Notes:

- 4. All outputs loaded; thresholds on input associated with output under test.
- 5. Maximum test duration 2.0ms, one output loaded at a time.

### **AC Electrical Characteristics for AC**

			T,	$egin{aligned} T_{A} &= +25^{\circ}C, \ C_{L} &= 50 pF \end{aligned}$		$T_A = -40$ °C to $+85$ °C, $C_L = 50$ pF		
Symbol	Parameter	V <sub>CC</sub> (V) <sup>(6)</sup>	Min.	Тур.	Max.	Min.	Max.	Units
t <sub>PLH</sub>	Propagation Delay	3.3	1.5	6.0	8.0	1.0	9.0	ns
	Data to Output	5.0	1.5	4.5	6.5	1.0	7.0	
t <sub>PHL</sub>	Propagation Delay	3.3	1.5	5.5	8.0	1.0	8.5	ns
	Data to Output	5.0	1.5	4.5	6.0	1.0	6.5	
t <sub>PZH</sub>	Output Enable Time	3.3	1.5	6.0	10.5	1.0	11.0	ns
		5.0	1.5	5.0	7.0	1.0	8.0	
t <sub>PZL</sub>	Output Enable Time	3.3	1.5	7.0	10.0	1.0	11.0	ns
		5.0	1.5	5.5	8.0	1.0	8.5	
t <sub>PHZ</sub>	Output Disable Time	3.3	1.5	7.0	10.0	1.0	10.5	ns
		5.0	1.5	6.5	9.0	1.0	9.5	
t <sub>PLZ</sub>	Output Disable Time	3.3	1.5	7.5	10.5	1.0	11.5	ns
		5.0	1.5	6.5	9.0	1.0	9.5	

#### Note:

6. Voltage range 3.3 is 3.3V  $\pm$  0.3V. Voltage range 5.0 is 5.0V  $\pm$  0.5V.

### **AC Electrical Characteristics for ACT**

			T <sub>A</sub>	\ = +25° Ε <sub>L</sub> = 50p	C, F	T <sub>A</sub> = -40°C C <sub>L</sub> =	to +85°C, 50pF	
Symbol	Parameter	$V_{CC}(V)^{(7)}$	Min.	Тур.	Max.	Min.	Max.	Units
t <sub>PLH</sub>	Propagation Delay, Data to Output	5.0	1.5	6.0	8.5	1.5	9.5	ns
t <sub>PHL</sub>	Propagation Delay, Data to Output	5.0	1.5	5.5	7.5	1.5	8.5	ns
t <sub>PZH</sub>	Output Enable Time	5.0	1.5	7.0	8.5	1.0	9.5	ns
t <sub>PZL</sub>	Output Enable Time	5.0	2.0	7.0	9.5	1.5	10.5	ns
t <sub>PHZ</sub>	Output Disable Time	5.0	2.0	8.0	9.5	2.0	10.5	ns
t <sub>PLZ</sub>	Output Disable Time	5.0	2.5	6.5	10.0	2.0	10.5	ns

#### Note:

7. Voltage range 5.0 is  $5.0V \pm 0.5V$ .

### Capacitance

Symbol	Parameter	Conditions	Тур.	Units
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = OPEN	4.5	pF
$C_{PD}$	Power Dissipation Capacitance	V <sub>CC</sub> = 5.0V	45.0	pF

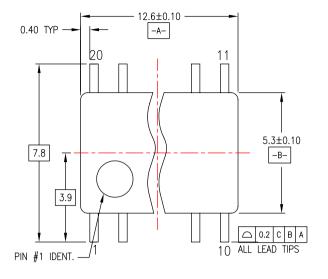
### **Physical Dimensions** 13.00 12.60 11.43 В 9.50 10.65 7.60 10.00 7.40 PIN ONE 0.35 INDICATOR **⊕** 0.25 **M** C B A LAND PATTERN RECOMMENDATION 2.65 MAX SEE DETAIL A 0.33 С 0.20 △ 0.10 C 0.30 0.10 NOTES: UNLESS OTHERWISE SPECIFIED (R0.10)A) THIS PACKAGE CONFORMS TO JEDEC GAGE PLANE MS-013, VARIATION AC, ISSUE E (R0.10) B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS. D) CONFORMS TO ASME Y14.5M-1994 1.27 0.40 SEATING PLANE E) LANDPATTERN STANDARD: SOIC127P1030X265-20L -(1.40)-DETAIL A SCALE: 2:1 F) DRAWING FILENAME: MKT-M20BREV3

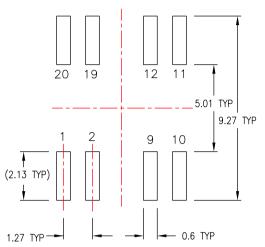
Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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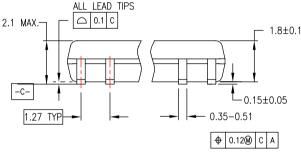
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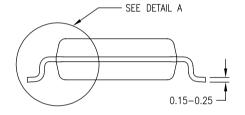
### Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATION





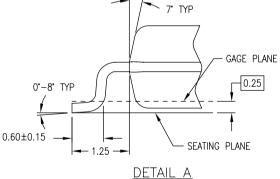
DIMENSIONS ARE IN MILLIMETERS

#### NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

  B. DIMENSIONS ARE IN MILLIMETERS.

  C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



M20DREVC

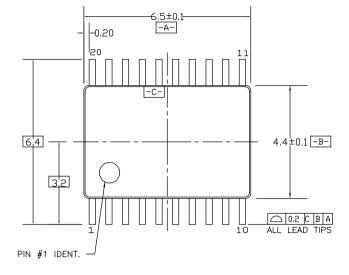
Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

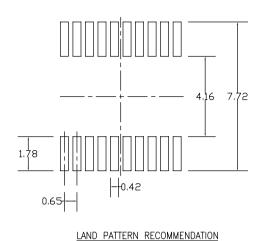
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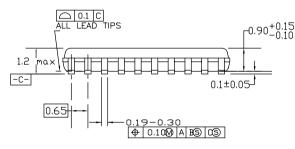
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### Physical Dimensions (Continued)









#### NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MD-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

## 

SEE DETAIL A

#### MTC20REVD1

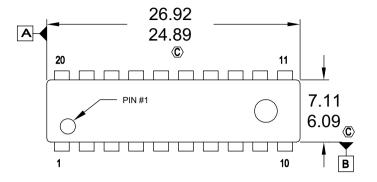
#### Figure 3. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

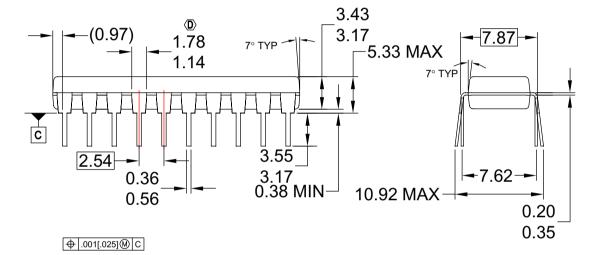
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#### Physical Dimensions (Continued)





NOTES:
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VARIATIONS AD.

B. ALL DIMENSIONS ARE IN MILLIMETERS

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MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED

(D) DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED

E. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

F. DRAWING FILE NAME: N20AREV8

Figure 4. 20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

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Definition of Terms					
Datasheet Identification	Product Status	Definition			
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.			
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.			
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